

Product Specification :		ISSUED BY:	Engineering Dep	
Subject :		Date Issued	2013/05/21	
1.50mm Pitch SCT1501 Series Conne	1.50mm Pitch SCT1501 Series Connector Specification			
This specification is referred to the 1	L.50mm series wire t	o board connec	tor	
IN	IDEX			
1. Scope				
2. Spec and Part number				
3. Disposal of Material and surface				
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5. Performance				
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7. SMT Infrared Reflow Condition				



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# 1. Scope

This Specification Covers the 1.50mm Pitch SCT1501 Series Connector Specification.

### 2. Spec and Part number

Specification	Production No.	Picture of Product
Terminal	SCT1501TPS126	NONE
Housing	SCT1501H-xxBWT102	NONE
Wafer	SCT1501WR-xxG0BE102 SCT1501WV-xxG0BE102	NONE

## 3. Disposal of Material and surface

Specification		Materials	Disposal of Surface
Terminal		Phosphor Bronze	Tin Plated: Over 70 $\mu^{\prime\prime}~$ .Nickel: Over 30 $\mu^{\prime\prime}~$ .
Housing		PA66	UL 94V-0
	Base	High Temperature Plastic	UL 94V-0
Wafer	PIN	Brass	Over Tin 70 $\mu^{\prime\prime}$ /Over 30 $\mu^{\prime\prime}$ Nickel
	Solder tab	Brass	Over Tin 70 $\mu^{\prime\prime}$ /Over 30 $\mu^{\prime\prime}$ Nickel

## (Please Refer to the Project drawing for the above Specification)

#### 4. Ratings and applicable wires

Item	Stand	ard		
Rated Voltage (Max.)	50V			
Rated Current (Max.)	1.0A	- [AC/DC]		
Ambient temperature Range $-25^{\circ}C^{*}+85^{\circ}C$				
Applicable wire insulation O.D	AWG 26#~32# Insulatio	AWG 26#~32# Insulation O.D. 1.20mm(Max.)		

\*Including terminal temperature rise.



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5.	5. PERFORMANCE <u>5-1. Electrical Performance.</u>					
		ltem	Test Condition	Requi	rement	
			Mate connectors, measure by dry circuit, 20mV MAX, 10mA. (Based upon EIA-364-06A).			
	5-1-1	Contact Resistance		20 millio Afte	tial: hms Max. r Test: hms Max.	
	5-1-2	Insulation Resistance	Mate connectors, apply 500V DC between adjacent terminal or ground. (Based upon EIA-364-21B/MIL-STD-202 Method 302 Cond.B)	500 Me	gohms Min.	
		Dielectric Strength	Mate connectors, apply 500V AC for 1 minute between adjacent terminal or ground. (Based upon EIA-364-20A/MIL-STD-202 Method 301)	No Breakdown and Flashover		
	5-1-4	Contact resistance on crimped portion	Crimp the applicable wire on to the terminal measure by dry circuit 20mV MAX, 10mA.	10 mill	iohms Max.	

# 5-1. Electrical Performance

	Item		Test Condition	Requirement
			Insert and withdraw Connectors at the speed rate of 25.4±3mm/minute.	
	Insertion & 5-2-1 Retention Force	Pull	Refer to paragraph 6	
			PUSH	



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bject:	4.50		Date Issue	d	2013	8/05/21
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5-2. Me	chanical Perform	ance.				
Item		Test Condition	Requireme	nt		
5-2-2	Terminal /Housing Retention Force	Apply axial pull out force at the rate of 25.4±3mm/minute terminal assembled in the housing.	6.86N {0.7kgf} Min.			
5-2-3	Terminal Insertion Force	Insert the crimped terminal into the housing.	9.8N {1.0kgf} Max.			
5-2-4	Pin Retention Force	Apply axial push force at the speed of 25.4±3mm/minute.	9.8N {1.00k	gf} Mi	n.	
		Fix the crimped terminal, apply axial pull out	AWG#	#28	#30	#32
	Tensile	force on the wire. (Do not crimp insulation part).	Spec.kgf. Min.	1.0	0.5	0.3
5-2-5 strength (Crimped connections)		ication				

## 5-3. Environmental Performance and Others.

ltem		Test Condition	Requir	ement
5-3-1	Repeated Insertion/ Withdrawal	When mated up to 50 cycles repeatedly by the rate of 10 cycles per minute.	Contact Resistance	30 milliohms Max.



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	ltem	Test Condition	Requir	ement
5-3-2	Temperature Rise	Carrying rated current load. (UL 1977)	Temperature rise	<b>30°</b> ℃ Max.
		Amplitude: 1.5mm P-P	Appearance	No Damage
5-3-3	Vibration	Sweep time: 10~55~10 HZ in 1 minute Duration: 2 hours in each X.Y.Z axials.	Contact Resistance	30 milliohms Max.
		(Based upon EIA-364-28B/MIL-STD-202 Method 213B Cond.A)	Discontinuity	1 micro- second Max.
			Appearance	No Damage
5-3-4	Shock	490m/s <sup>2</sup> {50G}, 3 strokes in each X.Y.Z. axes. (Based upon EIA-364-27B/MIL-STD-202 Method 213B Cond.A)	Contact Resistance	30 milliohms Max.
			Discontinuity	1 micro- second Max.
			Appearance	No Damage
5-3-5	Heat Resistance	85±2℃,96 hours. (Based upon MIL-STD-202 Method 108A Cond.A)	Contact Resistanc	30milliohms Max.
			Appearance	No Damage
5-3-6	Cold Resistance	-25±5℃,96 hours. ( Based upon EIA-364-105)	Contact Resistanc	30milliohms Max.
			Appearance	No Damage
		ty Temperature: 40±2°C Relative Humidity: 90~95% Duration: 96 hours (Based upon EIA-364-31A/MIL-STD-202 Method 103B Cond.B) Insulation Resistance		30milliohms Max.
5-3-7	Humidity			Must meet 5-1-3
				100Megohms Min.
		5 cycles of: a) -55 °C 30 minutes.	Appearance	No Damage
5-3-8	Temperature b) +85 °C 30 minutes.		Contact Resistance	30milliohms Max.



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Item Test Condition Requirement					
		24±1 hours exposure to a salt spray from the $5\pm1\%$ solution at $35\pm2\%$ . (Based upon	Appearance	No Damage	
5-3-9	Salt Spray	EIA-364-26A/MIL-STD-202 Method 101D Cond.B).	Contact Resistance	30milliohms Max.	
5-3-10	Solder- ability	Soldering Time: 5±0.5second. Solder Temperature: 245±5℃. (Based upon EIA-364-52)	Solder Wetting	95% of immersed area must show no voids, pin holes.	
5-3-11	Solder- Resistance	Soldering time:5~10 sec solder. Temperature:250+5/-5℃. (Based upon EIA-364-56A)	Appearance	No Damage	

# 6. INSERTION/WITHDRAWAL FORCE <Connector mating force>

No. of CKT	First Insertion (kgf Max.)	30 <sup>th</sup> Withdrawal (kgf Min.)	No. of CKT	First Insertion (kgf Max.)	30 <sup>th</sup> Withdrawal (kgf Min.)
2	2.5	0.2	9	6.0	0.9
3	3.0	0.3	10	6.5	1.0
4	3.5	0.4	11	7.0	1.1
5	4.0	0.5	12	7.5	1.2
6	4.5	0.6	13	8.0	1.3
7	5.0	0.7	14	8.5	1.4
8	5.5	0.8	15	9.0	1.5

Note:Insertion and Withdrawal for 30Cycles



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7. SMT SMT	INFRARED REFLOW CONDITION		
		+5/-5℃PEAK)	
	20~40S(230°C	Min)	
	90~120S 30S		
	(Per-heat 150~200℃) (Reflow)		
	TEMPERATURE CONDITION GRAPH/ (TEMPERATURE ON B	BOARD PATTERN	SIDE)
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